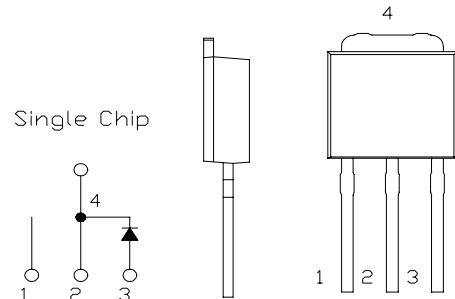


SBD Type : ESL03B03

OUTLINE DRAWING

FEATURES

- * TO-251AA Case
- * Extremely Low Forward Voltage drop
- * Low Power Loss, High Efficiency
- * High Surge Capability



Maximum Ratings

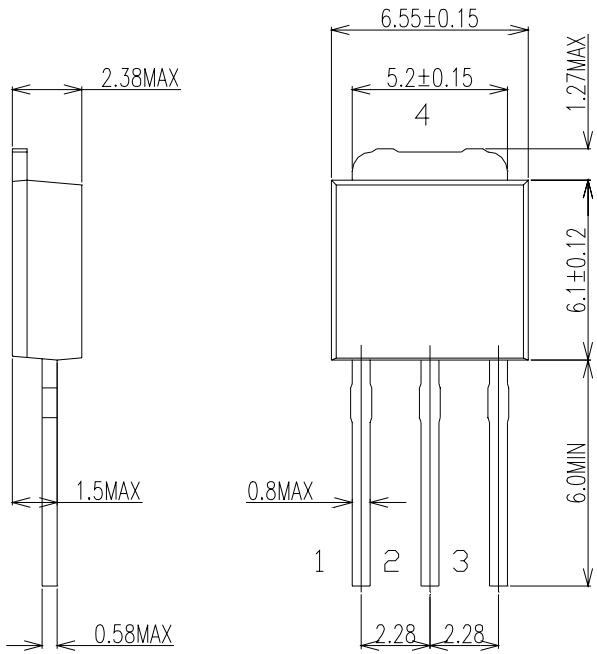
Approx Net Weight:0.35g

| Rating | Symbol | ESL03B03 | | | Unit |
|--------------------------------------|--------------|---------------|---|------------------------------------|------|
| Repetitive Peak Reverse Voltage | V_{RRM} | 30 | | | V |
| Average Rectified Output Current | I_o | 3.0 | $T_c=82^\circ C$ | 50Hz Half Sine Wave Resistive Load | A |
| RMS Forward Current | $I_{F(RMS)}$ | 4.71 | | | A |
| Surge Forward Current | I_{FSM} | 45 | 50Hz Half Sine Wave, 1cycle, Non-repetitive | | |
| Operating Junction Temperature Range | T_{jw} | - 40 to + 100 | | | °C |
| Storage Temperature Range | T_{stg} | - 40 to + 125 | | | °C |

Electrical • Thermal Characteristics

| Characteristics | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------------------|---------------|----------------------------------|-----|-----|------|------|
| Peak Reverse Current | I_{RM} | $T_j=25^\circ C, V_{RM}=V_{RRM}$ | - | - | 3.0 | mA |
| Peak Forward Voltage | V_{FM} | $T_j=25^\circ C, I_{FM}= 3 A$ | - | - | 0.47 | V |
| Thermal Resistance Junction to Case | $R_{th(j-c)}$ | - | - | - | 6 | °C/W |

ESL03B03 OUTLINE DRAWING (Dimensions in mm)



Single Chip

